

PCN Number: CO-22254	Contact: Elizabeth La Greca		
Date Issued: December 11th, 2018	Title: Director, Sales Operations		
PCN Effective Date: March 11th, 2019	Phone: 1-858-795-0106		
Product(s) Affected: PE42520	Email: pcn@psemi.com		
Sample Availability: December 11th, 2018			
Change Control Board Approval #: CO-22254			
Change Category:			
	☐ Shipping/Labeling		
☐ Design/Mask Change	☐ Equipment		
☐ Singulation Process	☐ Material		
Assembly Process	☐ Product Specification		
☐ Electrical Test	☐ Product End of Life		
☐ Manufacturing Site	Other - Ordering codes change		
Purpose of Change: To enable Lanis as the primary wafer fabrication site	for the DE 12520		
To enable Lapis as the primary wafer fabrication site	TOI THE FEAZUZU.		
Description of Change:			
Description of Change:			
MagnaChip closed their 150 mm wafer CMOS fab in a no disruption to supply, we have been working to tradapan. Magnachip and Lapis are qualified pSemi fabs	nsfer products from MagnaChip fab to Lapis fab in		
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Customer Acknowledgement of Receipt:			
☐ Change Denied	Name:		
(Include explanation in comments section below)	Title:		
☐ Change Approved	Company:		
	Date:		
	Signature:		
Customer Comments:			



Appendix A - Reliability Qualification Summary



PE42520

Reliability Summary Report

Part Number(s):	PE42520	Product Family:	RF Switch	
Package Type:	16L 3x3 QFN	MSL Rating:	MSL 3	
Technology Platform:	ULTRACMOS®5			
Reliability Summary:	Based on the results of reliability testing, the PE42520 has met the reliability requirements for Production.			

Table 1: Product Design Reliability Results

Test #	Test Performed	TEST METHOD/ Conditions	Duration	Sample Size	Result
1	High Temperature Operating Life (HTOL)	Mil-Std-883 M1005.9/ JESD22-A108 VDD= 5.5V; VCTL= 3.6V; TA = TJ= 150°C;	500 hrs.	1 lot x 77	Pass
2	ESD	Mil-Std-883 M3015 (All pins)	2.5kV	1 lot x 3	Pass
2 Human Body Model (HBM)	Mil-Std-883 M3015 (RF Pins Only)	4kV	1 lot x 3	Pass	
3	ESD Machine Model (MM)	JEDEC JESD22-A115	200V	1 lot x 3	Pass
4	ESD Charged Device Model (CDM)	JEDEC JESD22-C101	1000V	1 lot x 3	Pass





PE42520

Reliability Summary Report

Table 2: Package Reliability Results

Test #	Test Performed	TEST METHOD/ Conditions	Duration	Sample Size	Result
5	HTOL	Mil-Std-883 M1005.9/ JESD22-A108	500 hrs.	1 lot x 77	Pass
6	HTS	Mil-Std-883 M1008.2/ JESD22-A103 T _A = 150°C	1,000 hrs.	1 lot x 77	Pass
7	HAST	JESD22-A110 VDD= 3.3 V; VCTL= 3.3V; P _v = 2.270 atm;	96 hrs.	3 lots x 45	Pass
8	TC	Mil-Std-883 M1010.8/ JESD22-A104	500 cycs.	3 lots x 45	Pass
9	TS	JESD22-A105 T _A = -55°C to +125°C	100 cycs.	3 lots x 45	Pass
10	WBP	Mil-Std-883 M2011.8/ JESD22-B115	-	3 lots x 20	Pass
11	Physical Dimensions	Mil-Std-883 M2016/ JESD22-B100	-	3 lots x 10	Pass
12	Die Shear	Mil-Std-883 M2019.8	-	3 lots x 5	Pass
13	Solderability	Mil-Std-883 M2003.9/ JESD22-B102	-	3 lots x 10	Pass

Technology Reliability Report (DOC-81028)